

ST25 mediated handover firmware



Product status link

[STSW-ST25DV008](#)

Features

- NFC Forum mediated handover to connect a device to a Wi-Fi® network
- NFC Forum TNEP to communicate with an ST25DV-I2C Dynamic tag
- Firmware running on B-L4S5I-IOT01A board

Description

The ST25 mediated handover demonstration shows how an ST25DV-I2C NFC dynamic tag can ease the connection of a device to a Wi-Fi network, using a smartphone as a mediator.

This demonstration implements the NFC Forum mediated handover protocol to communicate the Wi-Fi network credentials to the device, and the TNEP protocol to manage the communication between the smartphone and the ST25DV-I2C NFC dynamic tag. The B-L4S5I-IOT01A board (orderable from www.st.com) is required to run the demonstration.

The firmware (STSW-ST25DV008), the Android™ application (STSW-ST25007) with its source code (STSW-ST25008) and the user manual are available on www.st.com.

License scheme

STSW-ST25DV008 package is delivered under the SLA0052 (Mix_MyLiberty) software license agreement. The provided software components come with the license scheme detailed in the following table.

Table 1. Software component license agreements

Software component	Owner	License
Project applications	STMicroelectronics	Proprietary
NDEF middleware		
TNEP middleware		

Software component	Owner	License
Board support package (BSP)	STMicroelectronics	BSD-3 Clause
HAL STM32L4		
STM32L4xx CMSIS	STMicroelectronics	Apache License V2
Cortex [®] -M CMSIS	Arm [®] (1)	Apache License V2

1. Arm is a registered trademark of Arm Limited (or its subsidiaries) in the US and/or elsewhere.



Revision history

Table 2. Document revision history

Date	Version	Changes
01-Dec-2020	1	Initial release.
06-May-2021	2	Updated Section Features and Section Description .



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